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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/786,925	02/24/2004	Takatoshi Tsujimura	JP920000098US	4884
7590 06/17/2004			EXAMINER	
David Aker			DUONG, TAI V	
23 Southern Road Hartsdale, NY 10530			ART UNIT	PAPER NUMBER
111111111111111111111111111111111111111			2871	
			DATE MAILED: 06/17/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

The MAILING DATE f this c mmunication app Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.	IS SET TO EXPIRE 3 MONTH(S) FROM	AV.			
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 Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period we Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b). 	cause the application to become ABANDONE	the mailing date of this communica D (35 U.S.C. § 133).	ition.			
Status						
1) Responsive to communication(s) filed on	_·					
· · · · · · · · · · · · · · · · · · ·	action is non-final.					
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
 4) Claim(s) 10-17 is/are pending in the application 4a) Of the above claim(s) is/are withdraw 5) Claim(s) 10-13 is/are allowed. 6) Claim(s) 14 and 16 is/are rejected. 7) Claim(s) 15 and 17 is/are objected to. 8) Claim(s) are subject to restriction and/or 	vn from consideration.					
Application Papers						
9) The specification is objected to by the Examine	r.					
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correcting 11) The oath or declaration is objected to by the Expression 11.						
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been receive (PCT Rule 17.2(a)).	on No. <u>09/682,002</u> . ed in this National Stage				
Attachmont(s)		•.				
 Attachment(s) 1) ∑ Notice of References Cited (PTO-892) 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) ∑ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 02/24/04. 	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:					

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The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 14 and 16 are rejected under 35 U.S.C. 102(b) as being anticipated by Park et al (US 5,478,766).

Note Figs. 5A-E and Fig. 6C which identically disclose the claimed method comprising the steps of: forming a pattern of a gate electrode 22 on an insulating substrate 21; sequentially depositing a gate insulating film 24 and a semiconductor layer 25 on said gate electrode and then forming a metal film (27, 28); depositing an ITO film (29, 30) in consideration of a pattern of said metal film to be patterned and in consideration of a pattern of a pixel electrode 30; and patterning said metal film by using said ITO film as a mask thus forming a source electrode 31 and a drain electrode 32 (col. 5, line 38 – col. 6, line 23). As to claim 16, note Fig. 6C.

Claims 15 and 17 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claims 10-13 are allowed over the prior art of record because none of the prior art discloses or suggests a method for manufacturing an active matrix substrate of the *top gate* type in which a source electrode, a drain electrode, a semiconductor layer, a gate insulating film and a gate electrode are sequentially deposited on an insulating substrate directly or indirectly, comprising the steps of: patterning a gate metal

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deposited on said gate insulating film by the use of a resist mask; patterning said gate insulating film and said semiconductor layer by using said patterned gate metal as a mask; forming an ITO film and patterning the ITO film by using a resist mask; and patterning said gate electrode by using said patterned ITO film as a mask.

Claims 15 and 17 are allowable over the prior art of record because none of the prior art discloses or suggests a method having the combination of the steps recited in claim 14 with the step of providing a protection film on said source and drain electrodes to interpose the ITO film therebetween, and patterning said semiconductor layer by using said protection film, or with the step of forming said metal film is for forming said metal film in the same pattern as that of the patterned gate insulating film.

Any inquiry concerning this communication should be directed to Tai Duong at telephone number (571) 272-2291.

The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

TOANTON PRIMARY EXAMINER

TVD

06/04